

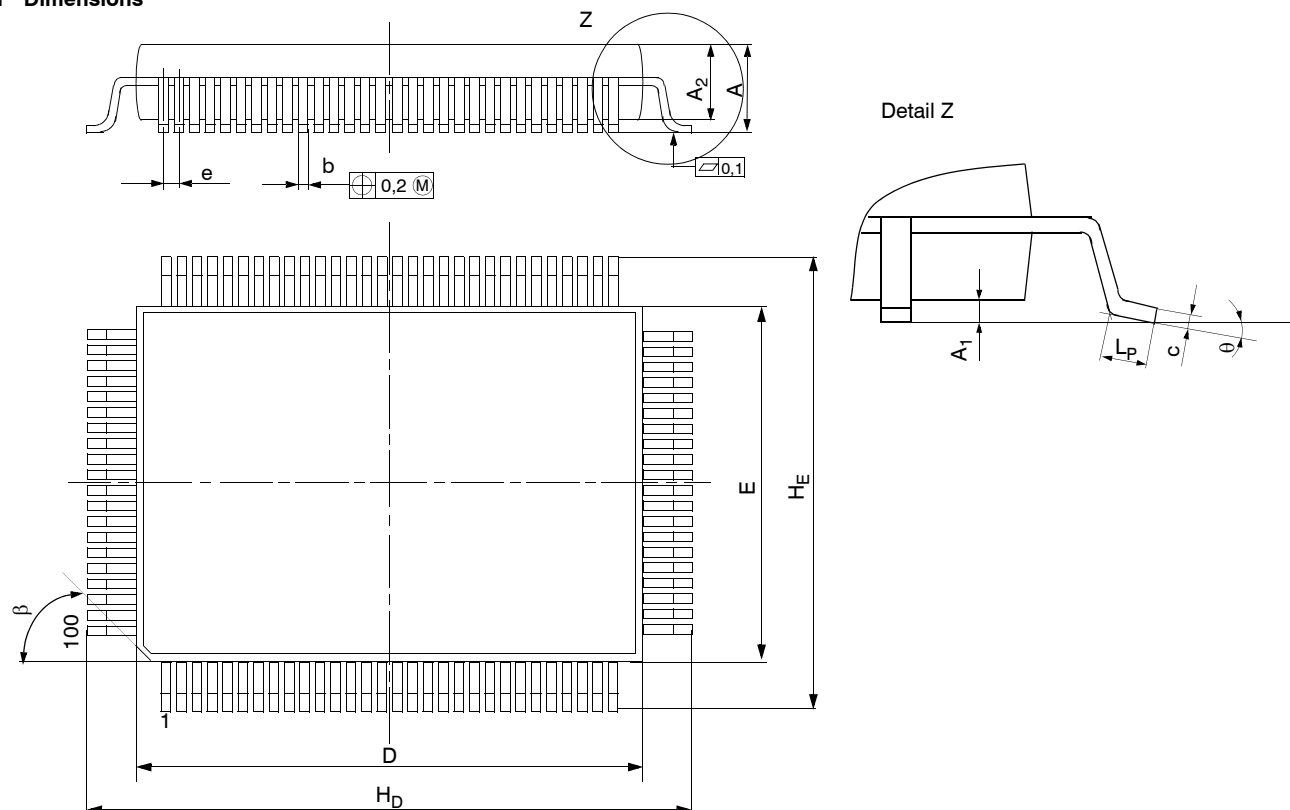
**MDS
718**

Supersedes
Edition 11.95

Dimensions in millimetres

Based on JEDEC JEP95: MO-112 CC-1

1 Dimensions



Dimensions of Sub-Group B1	
e_{nom}	0,65
A_{max}	3,40
b_{pmin}	0,22
b_{pmax}	0,40
H_{Emin}	17,65
H_{Emax}	18,15
H_{Dmin}	23,65
H_{Dmax}	24,15
L_{pmin}	0,63

2 Weight	≤ 1,6 g
3 Package Body Material	Low Stress Epoxy
4 Lead Material	FeNi-Alloy or Cu-Alloy
5 Lead Finish	solder plating
6 Lead Form	Z-bends

Dimensions of Sub-Group C1	
$A_{\min}$	2,75
$A_{1\min}$	0,10
$A_{1\max}$	0,50
$A_{2\min}$	2,60
$A_{2\max}$	3,00
$c_{\min}$	0,12
$c_{\max}$	0,23
$D_{\min}$	19,90
$D_{\max}$	20,10
$E_{\min}$	13,90
$E_{\max}$	14,10
$\theta_{\min}$	0°
$\theta_{\max}$	10°
β	45°

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